

IN THE SPECIFICATION:

Please replace paragraph number [0013] with the following rewritten paragraph:

[0013] Another embodiment of the present invention includes a method of culling semiconductor devices or bare semiconductor dice from a reject bin. The method includes retrieving a plurality of semiconductor devices or bare semiconductor dice from a reject bin, providing a plurality of multi-die handling devices having a plurality of pocket locations and assigning each ~~multi-die~~ multi-die handling device an ID code. Each semiconductor device or bare semiconductor die is placed in a pocket location of the plurality of pocket locations. The semiconductor devices or bare semiconductor dice are tested and a tray map file comprising test data is generated. The tray map file is stored in association with the ID code of the multi-die handling device. The method further includes reading the ID code on a multi-die handling device, retrieving the tray map file corresponding to the ID code, determining a tray matrix of the multi-die handling device, retrieving unique test data from the tray map file and marking each semiconductor device or bare semiconductor die of said plurality of semiconductor devices or bare semiconductor dice with the corresponding test data.

Please replace paragraph number [0018] with the following rewritten paragraph:

[0018] As shown in drawing FIG. 1, a JEDEC tray 100 consists of pocket locations 110 in rows and columns (X and Y-axis coordinates). Each pocket location 110 is assigned a unique coordinate number based on its X and Y-axis coordinates. In the example shown, pocket locations 110 receive a unique whole number (*i.e.*, 1.0, 2.0, 3.0) corresponding to its location along the X axis and a unique fractional number (*i.e.*, 0.1, 0.2, 0.3) corresponding to its location along the Y axis. While the current invention is described using a JEDEC tray 100, it will be understood by those of skill in the art that the invention is applicable to any multi-die handling device including multi-die handling devices having vertical carrier capabilities (*e.g.*, a multi-die handling device that can store dice along X, Y and Z coordinates). Further, as used herein, the terms “tray,” “carrier” and ~~“multi-die”~~ “multi-die handling device” are used interchangeably.

Please replace paragraph number [0019] with the following rewritten paragraph:

[0019] It will be further understood by those having skill in the field of this invention that the present invention is applicable to any IC device, including Dynamic Random Access Memory (DRAM)-~~IC's~~, ICs, Static Random Access Memory (SRAM)-~~IC's~~, ICs, Synchronous DRAM (SDRAM)-~~IC's~~, ICs, processor-~~IC's~~, ICs, Single In-Line Memory Modules-~~(SIMM's)~~, (SIMMs), Dual In-Line Memory Modules-~~(DIMM's)~~, (DIMMs), and other Multi-Chip Modules ~~(MCM's)~~, (MCMs).